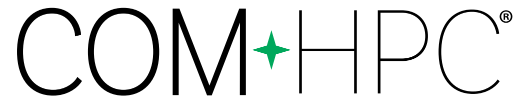
COM-HPC® SOLUTIONS

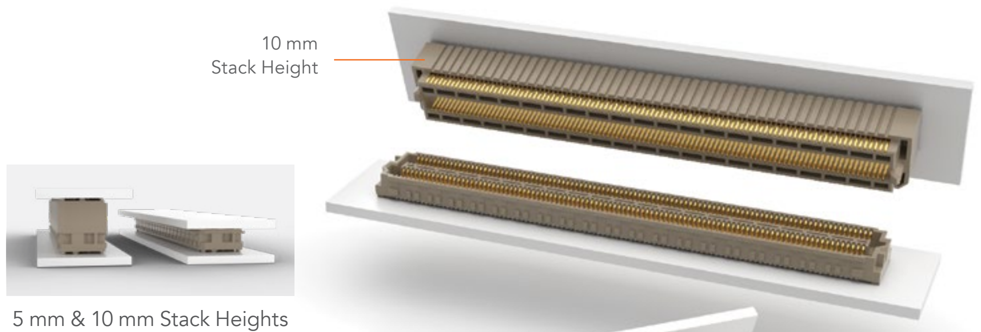
0.635 mm Pitch High-Speed, High-Density System

Samtec offers a high-density interconnect system that meets the COM-HPC® standard for high-performance Computer-On-Modules. COM-HPC® meets the growing demands for embedded systems to provide ultra-high speed performance and extended connectivity with limitless scalability.



HIGH-SPEED PERFORMANCE

- Up to 32 Gbps per channel
  - 4096 Gbps max aggregate
  - 2088 Gbps per square inch
- PCIe® 5.0 capable
- 100 Gb (4 x 25 Gb) Ethernet capable
- Up to 300 W at 11.4 – 12.6 Volts



5 mm & 10 mm Stack Heights

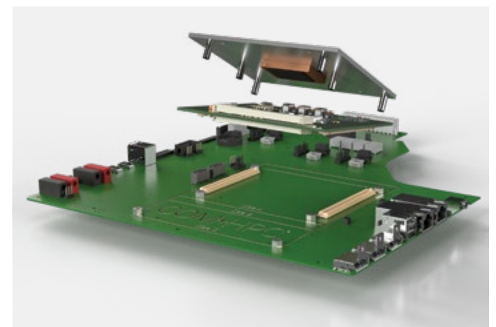
HIGH-DENSITY DESIGN

- High pin count interconnect system
  - 400 total pins
  - 4 x 100 design
- 0.635 mm pitch
  - Row 1 to row 2: 2.2 mm
  - Row 2 to row 3: 2.4 mm
  - Row 3 to row 4: 2.2 mm

APPLICATIONS

- Datacom & Telecom
- Embedded Edge Servers
- Industrial
- Medical Imaging
- 5G Wireless Infrastructure
- 5G Connected Vehicles

BGA Mount Increases Density & Performance



Typical COM-HPC® Module, Carrier & Heat Sink

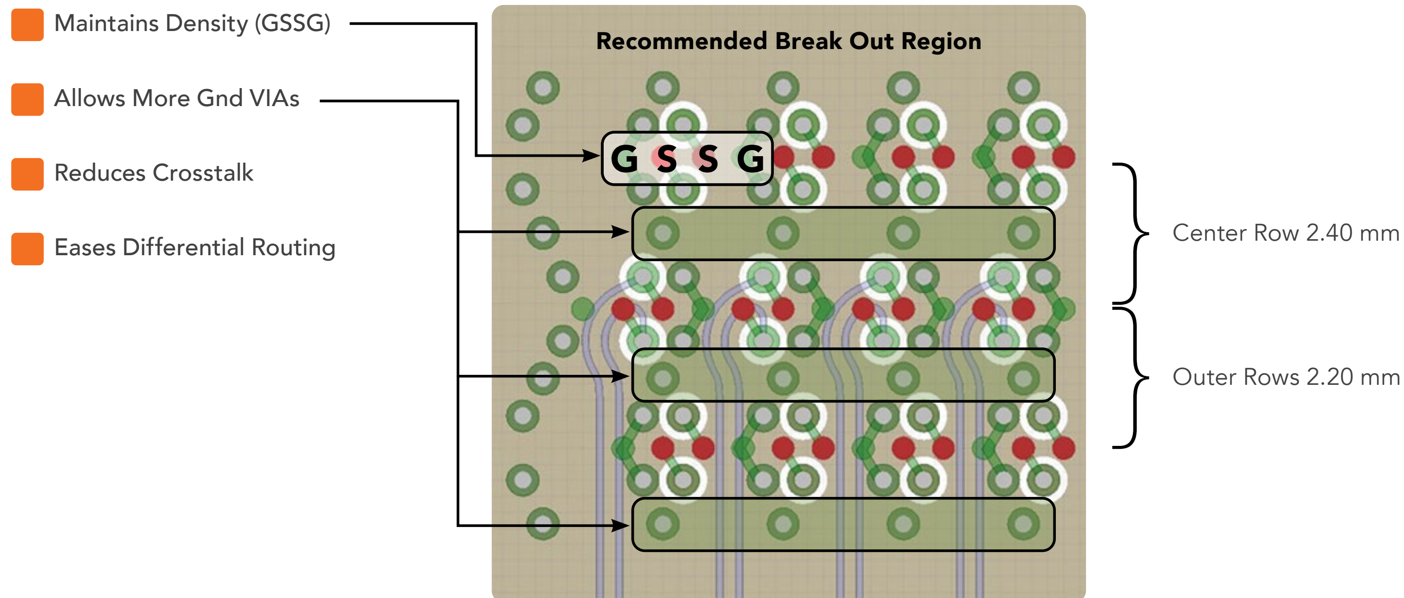
SYSTEM

- **ASP-209946-01 (Female) / ASP-214802-01 (Male)** – 5 mm Stack Height COM-HPC® Interconnects
- **ASP-209946-01 (Female) / ASP-209948-01 (Male)** – 10 mm Stack Height COM-HPC® Interconnects
- **ASP-222919-01** – 10 mm Stack Micro Jack Screw Precision Board Stacking Standoff

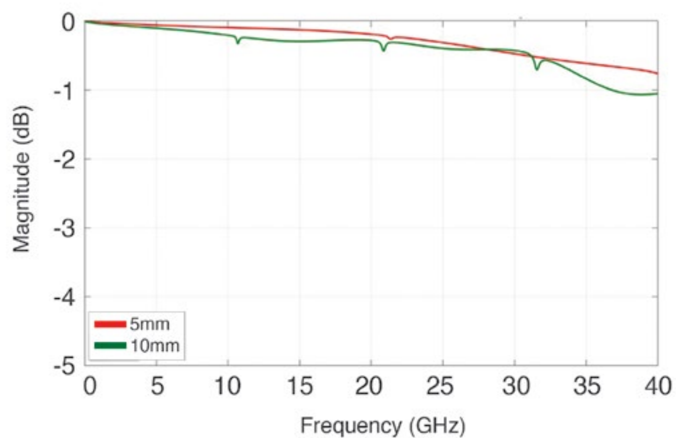
For more information, please visit samtec.com/COMHPC or email COMHPC@samtec.com.

TECHNICAL DATA

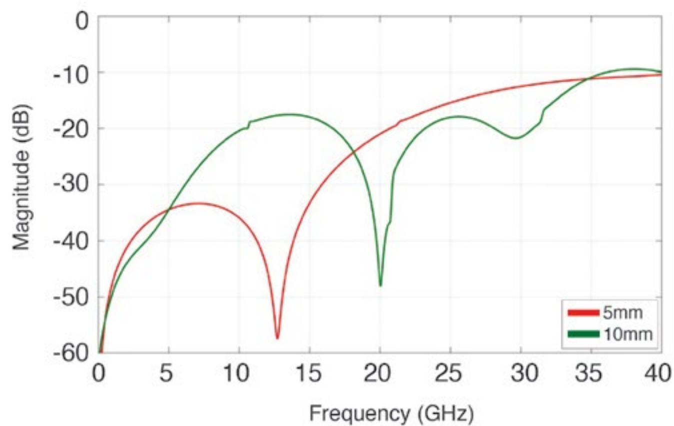
BENEFITS OF INCREASED ROW-TO-ROW SPACING



CONNECTOR-ONLY INSERTION LOSS (IL)



CONNECTOR-ONLY RETURN LOSS (RL)



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